



**NOTES: UNLESS OTHERWISE SPECIFIED**

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.

REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
-	1	REBUILD WITH CHANGE	GORAN P.
			DATE
			12-17-14

APPROVALS		<b>LINEAR TECHNOLOGY</b> 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL - FOR CUSTOMER USE ONLY	
PCB DES.	LT	TITLE: TOP ASSEMBLY DRAWING HIGH EFFICIENCY BOOST CONVERTER LOGIC SUPPLY	
APP ENG.	GORAN P.		
		SIZE	REV.
		N/A	1
		IC NO.	
		LTC1871EMS	
		DEMO CIRCUIT 414B	
		FILENAME:	SHT 1 OF 2
		DC414B-1.PCB	